

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes: a semiconductor element
2 bonded on a first metallic layer; a wire 4 for electrically
connecting an electrode pad of the semiconductor element to a
5 second metallic layer; and a resin package 7 for sealing said
semiconductor element. Rear surfaces of the first metallic
layer 8a and the second metallic layer 8b are flush with a bottom
of said resin package.

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